

Transtherm™ Thermal Conductive Adhesive Tape

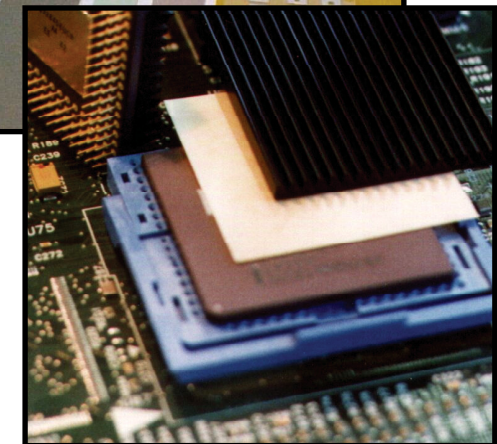
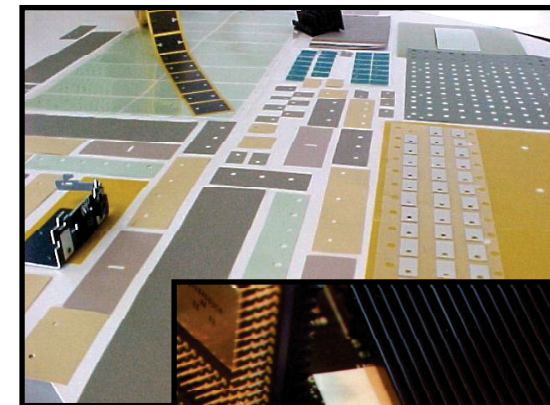
Transtherm™ Thermal Conductive Adhesive Tape is an acrylic based pressure sensitive adhesive with tailor-made ceramic particles that provide superior thermal performance with no curing required.

Features

- Low thermal resistance with selected ceramic filler
- Thermally conductive or electrically & thermally conductive versions available
- High insulation version available (> 5 KV)
- Easy to handle, easy to assemble
- Single sided or double sided pressure sensitive adhesive to replace mechanical fasteners
- Supported (Al, Polyimide carrier) and unsupported versions available in various thicknesses

Applications

- Heat sink to imaging ICs, GPU, DRAM chip, ADSL chip, etc.
- Power Conversion – Power IC to heat sink
- Consumable Electronics, PDP or LCD-TV
- Heat sink attachment to plastic molded / BGA packages on PCBA



Transtherm Thermal Conductive Adhesive Tape

Physical Properties	TAP003	TAP005	TAP 005HT	TAP 005 S	TAP 010 S	T2022	Test Method
Adhesive Properties	one sided	both sides	Both sides	Both sides	Both sides	transfer	
Color	yellow	yellow	yellow	yellow	yellow	white	Visual
Thermal Impedance (°C-In ² /Watt)	<0,3	<0,3	0,54	0,17	0,333	0,15	ASTM D5470 (modified)
Min. Continuous Use Temperature (°C)	-40	-40	-40	-40	-40	-40	MIL-I-49456A
Max. Continuous Use Temperatur (°C)	150	150	155	150	150	150	
Thermal Conductivity (W/mK)	0,6	>0,6	0,46	1,2	1,2	>0,8	ASTM D5470 modified
Dielectric Strength (K Volts, minimum)	>6	>6	>6	>6	>6	n/a	ASTM D149
Thickness (mm)	0,075	0,125	0,125	0,125	0,25	0,1	ASTM D 374
Thickness Tolerance (mm)	+/- 0,015	+/- 0,025	+/- 0,025	+/- 0,025	+/- 0,03	+/- 0,02	
Shear Strength (KPa)	840	840				n/a	ASTM D1002
Shear Strength after Soldering bath (KPa)	1120	1120				n/a	ASTM D1002
Elongation (%)	35	35				200	ASTM D 828
Flame Resistance (UL file E316839)	n/a	UL 94 VO		UL 94 VO	UL 94 VO	UL 94 VO	UL 94 VO
Construction / Material	Acrylic adhesive	Acrylic adhesive	Acrylic adhesive	Acrylic adhesive	Acrylic adhesive	Acrylic adhesive	
Substrate / Reinforcement	Polyimide	Polyimide	Polyimide	Polyimide	Polyimide		

Attention:

All data and values of this technical information have been ascertained with care. Taking into consideration the multiplicity of both usage conditions and the process and application technologies, the data and information supplied represent lead values of a non-binding nature so that no warranty claims can be derived there from. Above all, in addition to our general sales conditions, only written agreements are regarded as being binding.